

IN THE CLAIMS:

Please amend the claims as follows:

Claim 1. (cancelled)

Claim 2. (currently amended) A high-frequency multilayer circuit substrate comprising:

a plurality of at least three circuit layers, an inner circuit layer of which includes a ground conductor;

a via hole penetrating the plurality of circuit layers to be connected to each other;

a via hole metal pad provided around the via hole;

a planar impedance matching circuit connected to the via hole through the via hole metal pad; and

a microstrip line being a signal transmission line, formed in at least one of the circuit layers other than the inner circuit layer, connected to the planar impedance matching circuit, wherein

a characteristic impedance of a via hole connecting portion formed by the via hole, the via hole metal pad and the planar impedance matching circuit matches a characteristic impedance of the signal transmission line,

the planar impedance matching circuit includes an impedance matching ~~transmission~~ microstrip line, one end of which is connected to the via hole through the via hole metal pad and other end of which is directly connected to the

microstrip line being the signal transmission line, the via hole metal pad, the planar impedance matching circuit and the microstrip line being the signal transmission line ~~being are~~ located on the same circuit layer.

Claim 3. (currently amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the signal transmission line based on an adjusted width and length of the impedance matching ~~transmission-~~microstrip line.

Claim 4. (currently amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the planar impedance matching circuit is formed by the impedance matching ~~transmission-~~microstrip line and stubs which are connected to both sides of the impedance matching ~~transmission-~~microstrip line at the other end connected to the microstrip being the signal transmission line.

Claim 5. (currently amended) A high-frequency multilayer circuit substrate as set forth in claim 4, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the microstrip line being the signal transmission line based on an adjusted width and length of the impedance matching ~~transmission-~~microstrip line and a width and a length of each of the stubs.

Claim 6. (currently amended) A high-frequency multilayer circuit substrate as set forth in claim 2, wherein

the planar impedance matching circuit is formed by a plurality of impedance matching ~~transmission~~ microstrip lines having at least two different widths and connected in series to the via hole and the microstrip line being the signal transmission line.

Claim 7. (currently amended) A high-frequency multilayer circuit substrate as set forth in claim 6, wherein

the characteristic impedance of the via hole connecting portion matches the characteristic impedance of the microstrip line being the signal transmission line based on adjusted widths and lengths of the impedance matching ~~transmission~~ microstrip lines.